

Operating Procedures Carrier Mounting for STS Etcher

Rev. 9/11/01

SYSTEM REQUIREMENTS

1. The only materials allowed in the system are
Silicon Polysilicon
Silicon dioxide Photoresist
Silicon nitride

NO other materials may be on your wafer!!!

2. The system requires 100mm (4in) wafers. If you have smaller wafers or pieces you may use the ***STS Carrier Mounting Procedure*** to secure them to a carrier 100mm wafer.
3. If you intend to etch deeper than 200 microns, you must mount your sample to a carrier 100mm wafer using the ***STS Carrier Mounting Procedure***.

MOUNTING

1. On a 4-inch silicon wafer, spin PR 1827 at a slow speed for 30 seconds. Only spin the PR until it is evenly spread across the carrier wafer.
2. When the spin is completed and the carrier wafer is still on the chuck, position your sample wafer or piece on top of the carrier wafer. The surface to be etched should be facing upwards.
3. Bake 10 minutes in 110°C oven.

TIP: A lower helium leak up rate occurs when the polished side of the wafer is downward and unpolished side is used for mounting.